



SKIS50N65-T7

Trench Field stop Fast IGBT Co-packed half rated with Thin SiC Schottky Diode

Type	V_{CE}	I_C	$V_{CEsat}, T_{vj}=25^{\circ}C$	T_{vjmax}	Package
SKIS50N65-T7	650V	50A	1.4V	175°C	TO-247

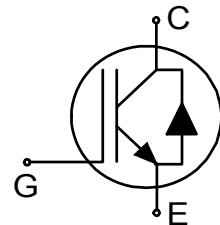
Features and Benefits

- Low switching losses due to the combination of trench field stop fast IGBT and thin SiC Schottky Diode
- Better efficiency and cost balance than SiC MOSFET solution
- High ruggedness



Applications

- Charger
- Solar inverter
- Energy storage
- Industrial UPS



	Parameter		Unit
V_{CE}	Max Collector-Emitter Voltage	650	V
$I_{C(Nominal)}$	Max DC Collector Current	50	A
V_f	SiC Schottky Diode Typical Forward Voltage at 40A	1.75	V
Q_c	SiC Schottky Diode Total Capacitance	40.5	nC



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Maximum Ratings

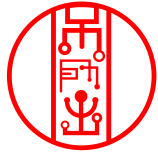
	Parameter	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage	650	—	—	V
I_C	DC collector current limited by T_{jmax}				
	$T_c = 25^\circ\text{C}$	—	—	100	A
	$T_c = 100^\circ\text{C}$	—	—	50	A
I_F	Diode Forward current, limited by T_{jmax}				
	$T_c = 25^\circ\text{C}$	—	—	100	A
	$T_c = 100^\circ\text{C}$	—	—	50	A
V_{GE}	Continuous Gate-emitter voltage	-20	—	20	V
V_{GE}	Transient Gate-emitter voltage	-30	—	30	V
I_{Fpuls}	Diode Pulsed Current, t_p limited by T_{jmax} $t_p = 10$ ms, Half Sine Wave	—	—	130	A
T_{sc}	Short Circuit Withstand Time, $V_{GE} = 15\text{V}$, $V_{CE} \leq 600\text{V}$, $T_j \leq 150^\circ\text{C}$	—	—	10	μs
T_{vj}	Operating junction temperature	-40	—	175	$^\circ\text{C}$
T_{stg}	Storage temperature -	-55	—	150	$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Max. Value	Unit
IGBT thermal resistance junction - case	$R_{\theta(j-c)}$	0.4	K/W
Diode thermal resistance, junction - case	$R_{\theta(j-c)}$	1.4	K/W
Thermal resistance, junction - ambient	$R_{\theta(j-a)}$	38	K/W

Static Characteristics. $T_j=25^\circ\text{C}$, unless otherwise specified

	Parameter	Min.	Typ.	Max.	Unit	Conditions
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage	650	—	—	V	
$V_{CE(sat)}$	Collector-to-Emitter Saturated Voltage	— —	1.4 1.8	1.8 —	V	$V_{GE} = 15\text{V}$, $I_C = 50\text{A}$, $T_j = 25^\circ\text{C}$ $T_j = 175^\circ\text{C}$
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	4.2	5.2	6.2	V	$I_C = 250\mu\text{A}$, $V_{GE} = V_{CE}$
I_{CES}	Zero Gate Voltage Collector Current	— —	— —	1 5	mA	$V_{CE} = 650\text{V}$, $V_{GE} = 0\text{V}$, $T_j = 25^\circ\text{C}$ $T_j = 175^\circ\text{C}$
I_{GES}	Gate Emitter Leakage Current	—	—	200	nA	$V_{CE} = 0\text{V}$, $V_{GE} = 20\text{V}$
C_{ies}	Input Capacitance	—	4845	—	pF	$V_{GE} = 0\text{V}$, $V_{CE} = 25\text{V}$, $f = 1\text{MHz}$
C_{oes}	Output Capacitance	—	264	—		
C_{res}	Reverse Transfer Capacitance	—	35	—		
Q_g	Gate charge	—	86	—	nC	$V_{CC} = 520\text{V}$, $I_C = 50\text{A}$, $V_{GE} = 15\text{V}$



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Switching Characteristic, Inductive Load ($T_J=25^{\circ}\text{C}$)

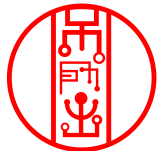
Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Turn-on delay time	$t_{d(on)}$	—	50	—	ns	$V_{CC} = 400\text{V}$, $I_C = 50\text{A}$, $V_{GE} = 0/15\text{V}$, $R_g=10\Omega$
Rise time	t_r	—	80	—	ns	
Turn-off delay time	$t_{d(off)}$	—	172	—	ns	
Fall time	t_f	—	74	—	ns	
Turn-on energy E_{on}	E_{on}	—	1.45	—	mJ	
Turn-off energy	E_{off}	—	1.27	—	mJ	
Total switching energy	E_{ts}	—	2.72	—	mJ	

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Turn-on delay time	$t_{d(on)}$	—	47	—	ns	$V_{CC} = 400\text{V}$, $I_C = 25\text{A}$, $V_{GE} = 0/15\text{V}$, $R_g=10\Omega$
Rise time	t_r	—	22	—	ns	
Turn-off delay time	$t_{d(off)}$	—	205	—	ns	
Fall time	t_f	—	15	—	ns	
Turn-on energy E_{on}	E_{on}	—	0.44	—	mJ	
Turn-off energy	E_{off}	—	0.37	—	mJ	
Total switching energy	E_{ts}	—	0.81	—	mJ	

Switching Characteristic, Inductive Load ($T_J=150^{\circ}\text{C}$)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Turn-on delay time	$t_{d(on)}$	—	47	—	ns	$V_{CC} = 400\text{V}$, $I_C = 50\text{A}$, $V_{GE} = 0/15\text{V}$, $R_g=10\Omega$
Rise time	t_r	—	74	—	ns	
Turn-off delay time	$t_{d(off)}$	—	188	—	ns	
Fall time	t_f	—	74	—	ns	
Turn-on energy E_{on}	E_{on}	—	1.45	—	mJ	
Turn-off energy	E_{off}	—	1.43	—	mJ	
Total switching energy	E_{ts}	—	2.88	—	mJ	

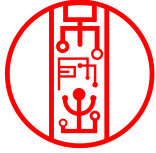
Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Turn-on delay time	$t_{d(on)}$	—	44	—	ns	$V_{CC} = 400\text{V}$, $I_C = 25\text{A}$, $V_{GE} = 0/15\text{V}$, $R_g=10\Omega$
Rise time	t_r	—	27	—	ns	
Turn-off delay time	$t_{d(off)}$	—	230	—	ns	
Fall time	t_f	—	18	—	ns	
Turn-on energy E_{on}	E_{on}	—	0.48	—	mJ	
Turn-off energy	E_{off}	—	0.55	—	mJ	
Total switching energy	E_{ts}	—	1.03	—	mJ	



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Diode Characteristic

	Parameter	Min.	Typ.	Max.	Unit	Conditions
V _f	Forward Voltage	—	1.35	1.55	V	I _c =20A, T _J = 25°C
		—	1.75	—		I _c =40A, T _J = 25°C
		—	1.61	—		I _c =20A, T _J = 150°C
		—	2.42	—		I _c =40A, T _J =150°C
Q _c	Total Capacitive Charge	—	40.5	—	nC	V _R =400V
C	Total Capacitance	—	854	—	pF	V _R =0V, T _J =25°C, f=1MHz
		—	74	—		V _R =200V, T _J =25°C, f=1MHz
		—	72	—		V _R =400V, T _J =25°C, f=1MHz



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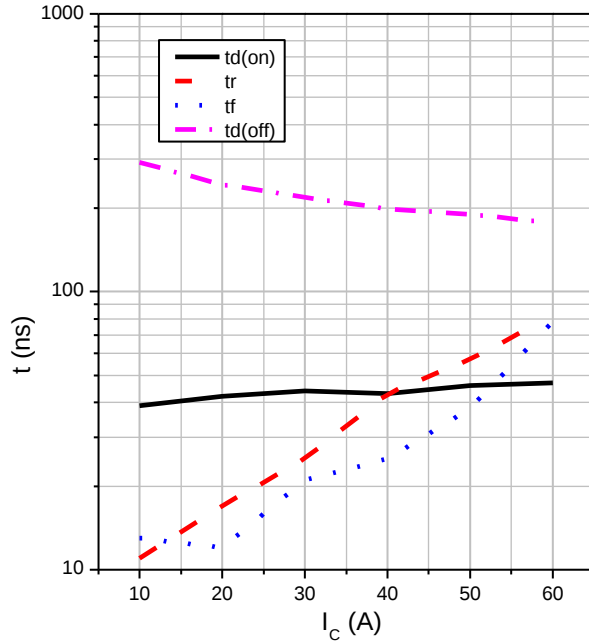


Figure 3. Typical switching times as a function of collector current
(inductive load, $T_{vj}=150^{\circ}\text{C}$, $V_{CE}=400\text{V}$, $V_{GE}=15/0\text{V}$, $R_G=10\Omega$, Dynamic test circuit in Figure E)

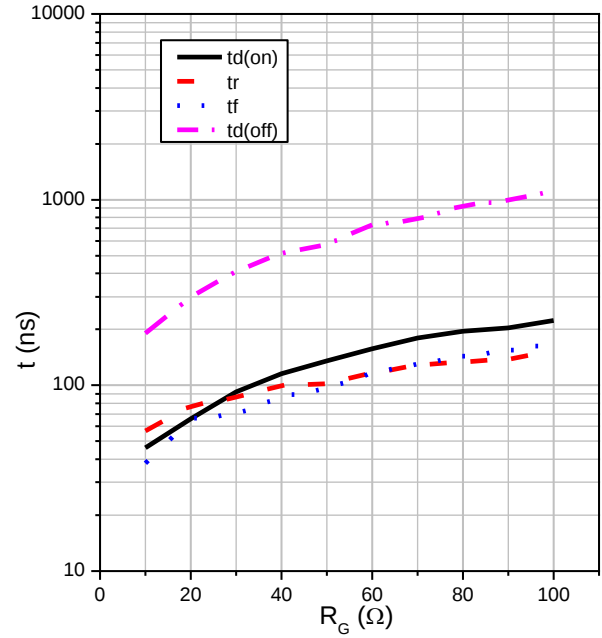


Figure 4. Typical switching times as a function of gate resistor
(inductive load, $T_{vj}=150^{\circ}\text{C}$, $V_{CE}=400\text{V}$, $V_{GE}=15/0\text{V}$, $I_C=50\text{A}$, Dynamic test circuit in Figure E)

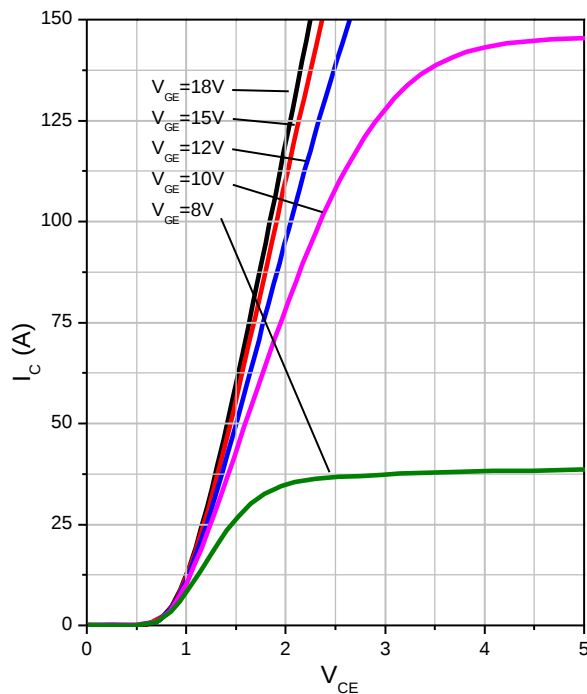


Figure 1. Typical output characteristic ($T_{vj}=25^{\circ}\text{C}$)

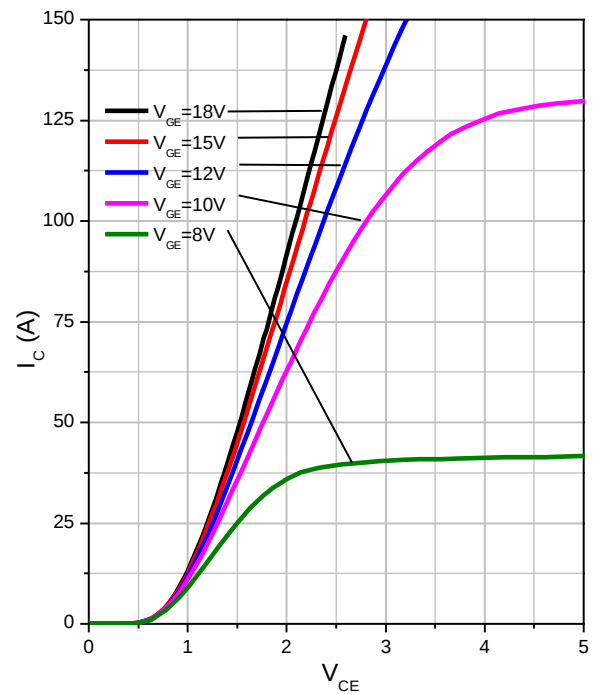
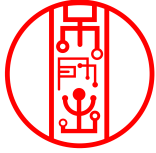


Figure 2. Typical output characteristic ($T_{vj}=150^{\circ}\text{C}$)



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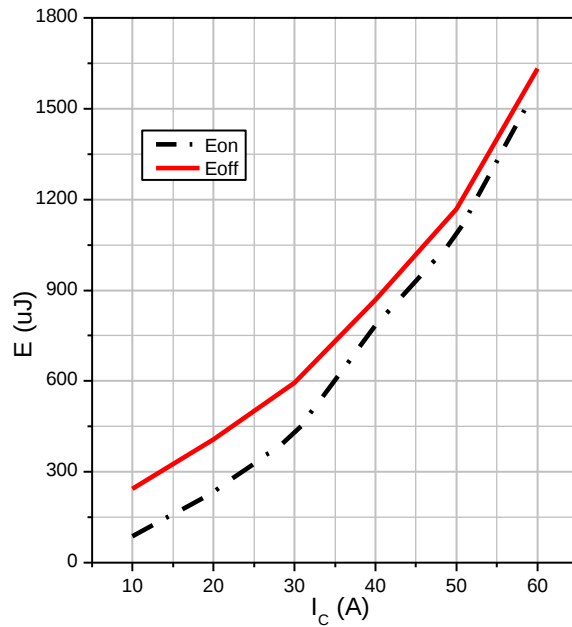


Figure 5. Typical switching energy losses as a function of collector current
(inductive load, $T_{vj}=150^{\circ}\text{C}$, $V_{CE}=400\text{V}$, $V_{GE}=15/0\text{V}$, $R_G=10\Omega$, Dynamic test circuit in Figure E)

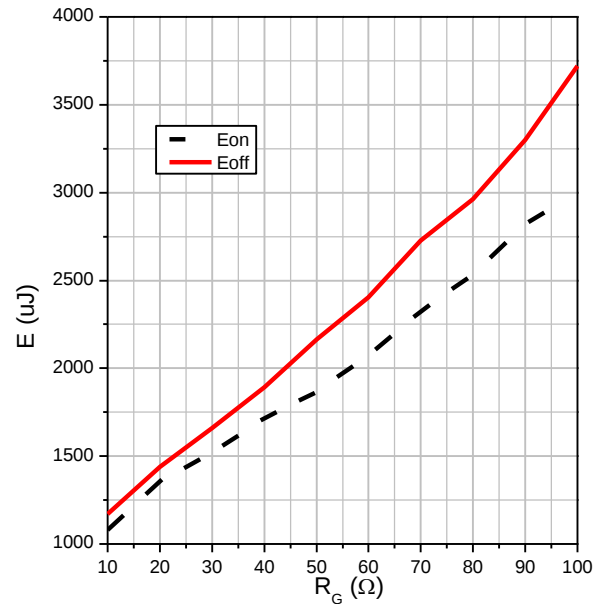


Figure 6. Typical switching energy losses as a function of gate resistor
(inductive load, $T_{vj}=150^{\circ}\text{C}$, $V_{CE}=400\text{V}$, $V_{GE}=15/0\text{V}$, $I_C=50\text{A}$, Dynamic test circuit in Figure E)

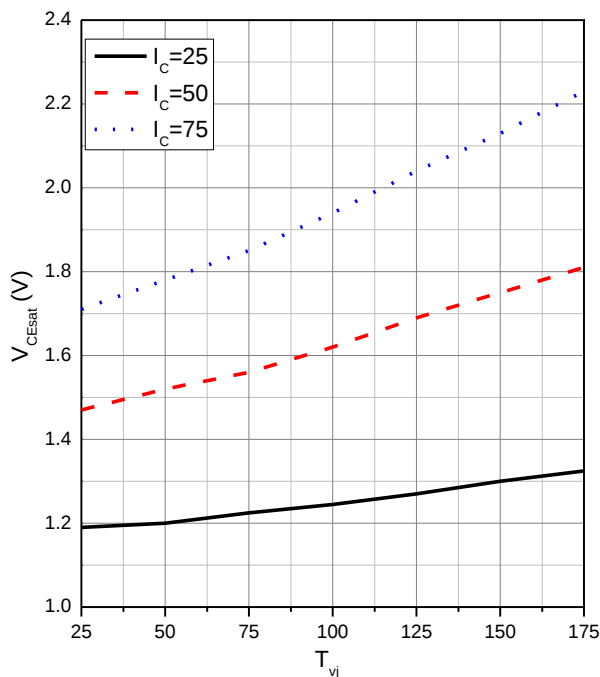


Figure 7. Typical collector-emitter saturation voltage as a function of junction temperature ($V_{GE}=15\text{V}$)

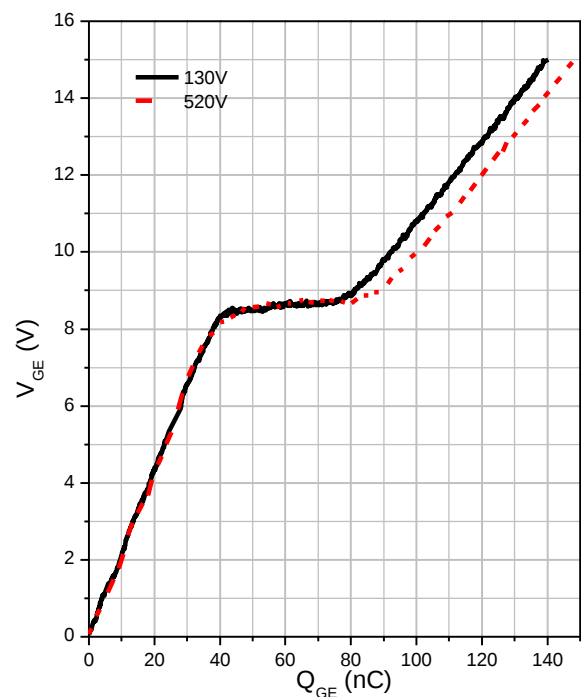
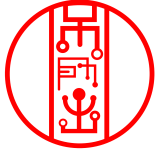


Figure 8. Typical gate charge ($I_C=50\text{A}$)



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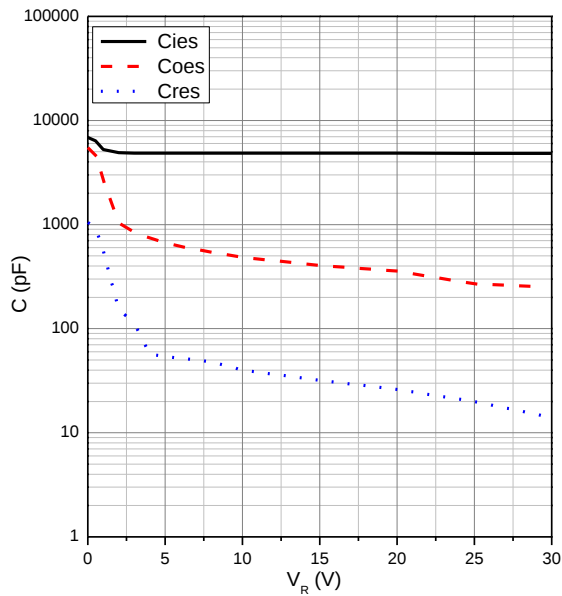


Figure 9. Typical capacitance as a function of collector-emitter voltage ($V_{GE}=0V$, $f=250kHz$)

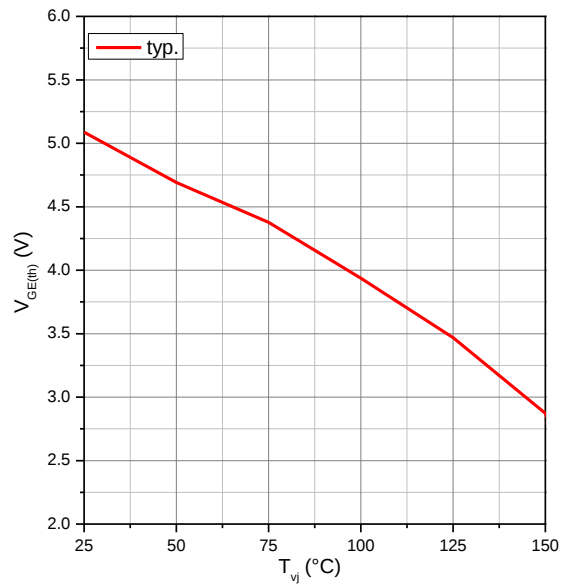


Figure 10. Gate-emitter threshold voltage as a function of junction temperature ($I_C=0.25mA$)

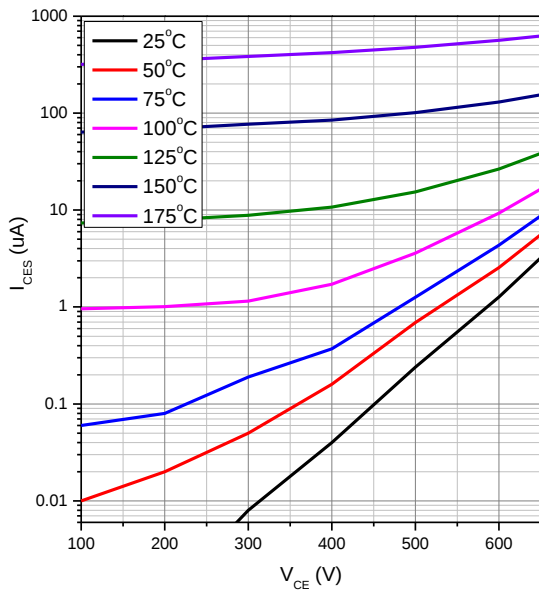


Figure 11. Typ. reverse current vs. reverse voltage as a function of T_{vj}

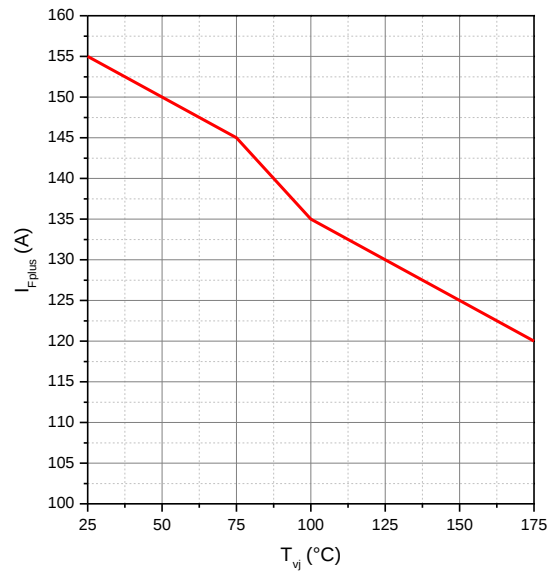
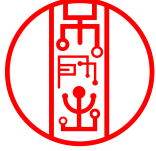


Figure 12. Maximum pulse current as a function of junction temperature



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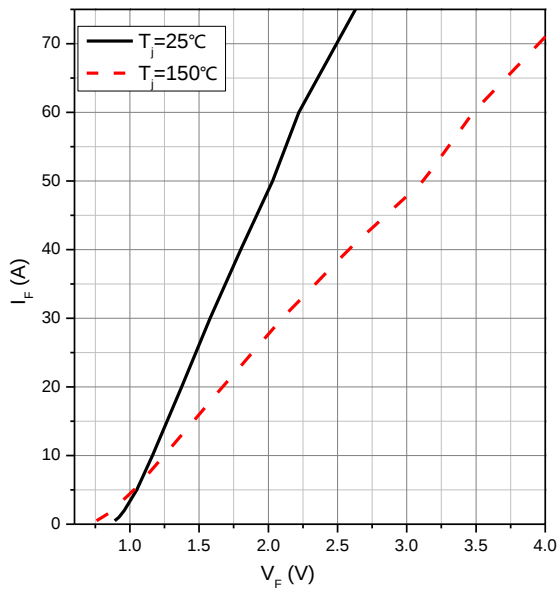


Figure 13. Typical diode forward current as a function of forward voltage

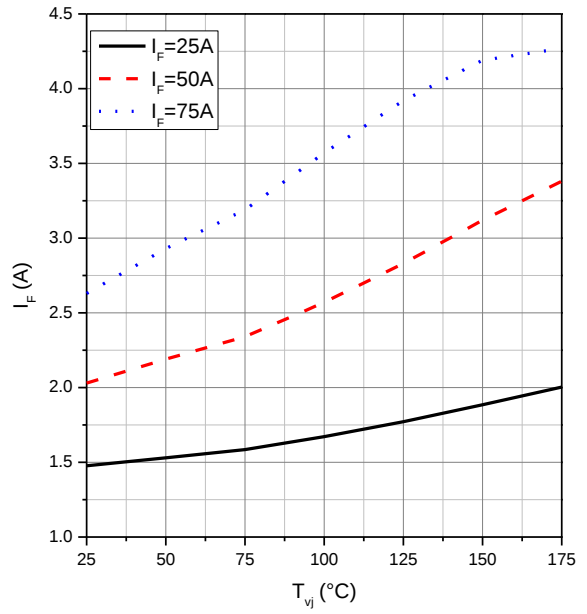
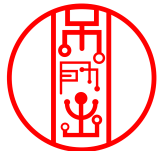
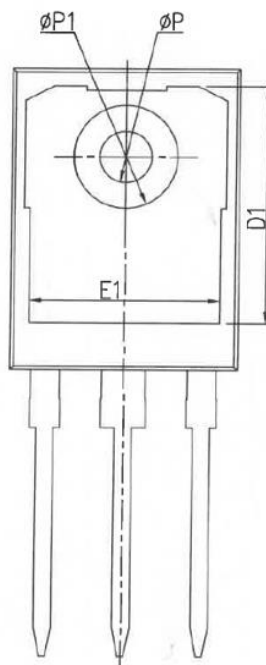
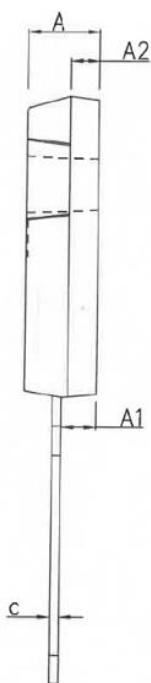
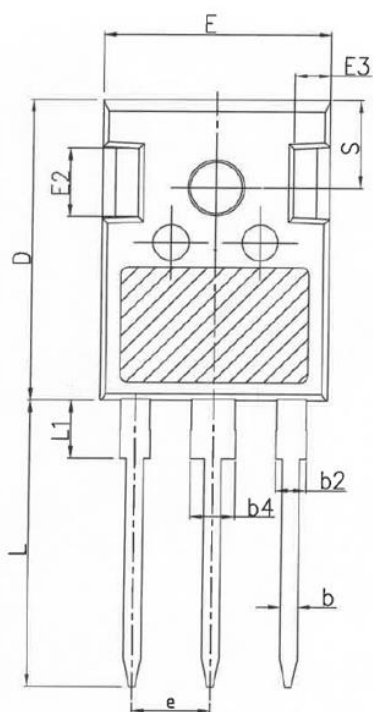


Figure 14 Typical diode forward voltage as a function of junction temperature



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TO-247 PACKAGE OUTLINE



COMMON DIMENSIONS

SYMBOL	mm		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.21	2.41	2.59
A2	1.85	2.00	2.15
b	1.11	1.21	1.36
b2	1.91	2.01	2.21
b4	2.91	3.01	3.21
c	0.51	0.61	0.75
D	20.70	21.00	21.30
D1	16.25	16.55	16.85
E	15.50	15.80	16.10
E1	13.00	13.30	13.60
E2	4.80	5.00	5.20
E3	2.30	2.50	2.70
e	5.44BSC		
L	19.62	19.92	20.22
L1	-	-	4.30
ØP	3.40	3.60	3.80
ØP1	-	-	7.30
S	6.15BSC		